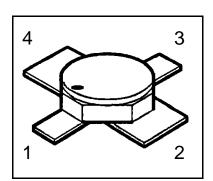


HiRel NPN Silicon RF Transistor

- HiRel Discrete and Microwave Semiconductor
- For low noise, high-gain broadband amplifiers at collector currents from 2mA to 30mA.
- Hermetically sealed microwave package
- f_T= 8 GHz
 F = 2.3 dB at 2 GHz
- **@esa** qualified
- ESA/SCC Detail Spec.

No.: 5611/006



ESD: Electrostatic discharge sensitive device, observe handling precautions!

Туре	Marking	Ordering Code	Pin Configuration		Package		
BFY183 (ql)	-	see below	С	Е	В	Е	Micro-X1

(ql) Quality Level: P: Professional Quality, Ordering Code: Q62702F1609
H: High Rel Quality, Ordering Code: on request
S: Space Quality, Ordering Code: on request
ES: ESA Space Quality, Ordering Code: Q62702F1713

(see order instructions for ordering example)



Maximum Ratings

Parameter	Symbol	Values	Unit V	
Collector-emitter voltage	V_{CEO}	12		
Collector-emitter voltage, V _{BE} =0	V_{CES}	20	V	
Collector-base voltage	V_{CBO}	20	V	
Emitter-base voltage	V_{EBO}	2	V	
Collector current	I _C	65	mA	
Base current	I _B	5 ^{1.)}	mA	
Total power dissipation, $T_S \leq 99^{\circ}C^{2.)}$	P _{tot}	450	mW	
Junction temperature	T _j	200	°C	
Operating temperature range	T_{op}	-65+200	°C	
Storage temperature range	T_{stg}	-65+200	°C	
Thermal Resistance	•	-	•	
Junction-soldering point ^{2.)}	R _{th JS}	< 225	K/W	

Notes.:

Electrical Characteristics

at T_A =25°C; unless otherwise specified

Parameter	Symbol	Values		Unit	
		min.	typ.	max.	
DC Characteristics					
Collector-base cutoff current	I _{CBO}	-	-	100	μΑ
$V_{CB} = 20 \text{ V}, I_{E} = 0$					
Collector-emitter cutoff current	I _{CEX}	-	-	300	μΑ
$V_{CE} = 12 \text{ V}, I_B = 0.3 \mu A^{-1.3}$					
Collector-base cutoff current	I _{CBO}	-	-	50	nA
$V_{CB} = 10 \text{ V}, I_{E} = 0$					
Emitter base cuttoff current	I _{EBO}	-	-	25	μΑ
$V_{EB} = 2 \text{ V}, I_{C} = 0$					
Emitter base cuttoff current	I _{EBO}	-	-	0.5	μΑ
$V_{EB} = 1 \text{ V}, I_{C} = 0$					

Notes:

1.) This Test assures V(BR)CE0 > 12V

¹⁾ The maximum permissible base current for $\rm V_{FBE}$ measurements is 20mA (spot-measurement duration < 1s)

²⁾ $T_{\mbox{\scriptsize S}}$ is measured on the collector lead at the soldering point to the pcb.



Electrical Characteristics (continued)

Parameter	Symbol		Values	Unit	
		min.	typ.	max.	
DC Characteristics					
Base-Emitter forward voltage	V_{FBE}	-	-	1	V
$I_E = 30 \text{ mA}, I_C = 0$					
DC current gain	h _{FE}	55	90	160	-
$I_{\rm C} = 5 \text{ mA}, V_{\rm CE} = 6 \text{ V}$					
AC Characteristics					
Transition frequency	f_{T}				GHz
$I_C = 20$ mA, $V_{CE} = 5$ V, $f = 500$ MHz		6,5	7.5	-	
$I_C = 25 \text{ mA}, V_{CE} = 8 \text{ V}, f = 500 \text{ MHz}$		-	8	-	
Collector-base capacitance	C _{CB}	-	0.32	0.44	pF
$V_{CB} = 10 \text{ V}, V_{BE} = \text{vbe} = 0, f = 1 \text{ MHz}$					
Collector-emitter capacitance	C_{CE}	-	0.34	-	pF
$V_{CE} = 10 \text{ V}, V_{BE} = \text{vbe} = 0, f = 1 \text{ MHz}$					
Emitter-base capacitance	C_{EB}	-	1.1	1.4	pF
$V_{EB} = 0.5V$, $V_{CB} = vcb = 0$, $f = 1 MHz$					
Noise Figure	F	-	2.3	2.9	dB
I_C = 8 mA, V_{CE} = 5 V, f = 2 GHz, Z_S = Z_{Sopt}					
Power gain	Gma 1.)	12.5	14	-	dB
$I_C = 20 \text{ mA}, V_{CE} = 5V, f = 2 \text{ GHz}$					
$Z_S = Z_{Sopt}$, $Z_L = Z_{Lopt}$					
Transducer gain	$ S_{21e} ^2$	9	10,5	-	dB
$I_C = 20 \text{ mA}, V_{CE} = 5 \text{ V}, f = 2 \text{ GHz}$					
$Z_S = Z_L = 50 \Omega$					
Output Power	P _{OUT}	13.5	14.5	-	dBm
$I_C = 30$ mA, $V_{CE} = 5$ V, $f = 2GHz$, $P_{IN} = 7dBm$					
$Z_S = Z_L = 50 \Omega$					

Notes.:

1)
$$G_{ma} = \left| \frac{S21}{S12} \right| (k - \sqrt{k^2 - 1}), \quad G_{ms} = \left| \frac{S21}{S12} \right|$$



Order Instructions:

Full type variant including quality level must be specified by the orderer. For *HiRel* Discrete and Microwave Semiconductors the ordering code specifies device family and quality level.

Ordering Form:

Ordering Code: Q.....

BFY183 (ql)

(ql): Quality Level

Ordering Example:

Ordering Code: Q62702F1713

BFY183 ES

For BFY193 in ESA Space Quality Level

Further Informations:

See our WWW-Pages:

- Wireless Semiconductors

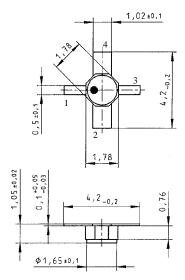
http://www.infineon.com

- HiRel Discrete and Microwave Semiconductors

www.infineon.com/cgi/ecrm.dll/ecrm/scripts/prod_ov.jsp?oid=16149&cat_oid=-8154



Micro-X1 Package



Published by Infineon Technologies Wireless, Discretes Products, Marketing, P.O.Box 801709, D-81617 Munich.

\tilde{a} Infineon Technologies AG 1998. All Rights Reserved.

As far as patents or other rights of third parties are concerned, liability is only assumed for components per se, not for applications, processes and circuits implemented within components or assemblies.

The information describes the type of component and shall not be considered as assured characteristics.

Terms of delivery and rights to change design reserved.

For questions on technology, delivery and prices please contact the Offices of Semiconductor Group in Germany or the Infineon Technologies Companies and Representatives woldwide (see address list).

Due to technical requirements components may contain dangerous substances. For information on the type in question please contact your nearest Infineon Technologies Office, Semiconductor Group.

Infineon Technologies Semiconductors is a certified CECC and QS9000 manufacturer (this includes ISO 9000).

Semiconductor Group 5 of 5 Draft B, Jul. 01